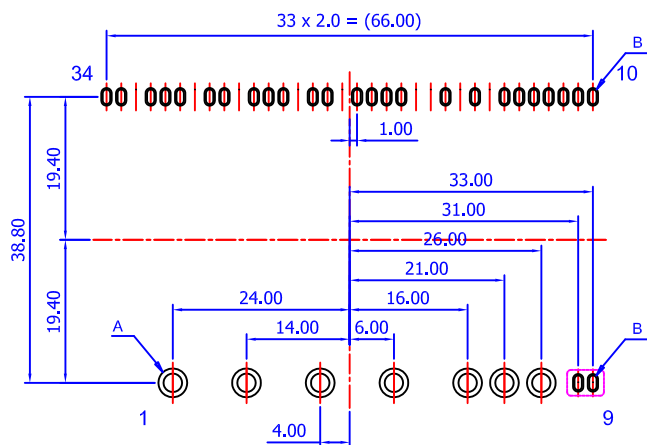
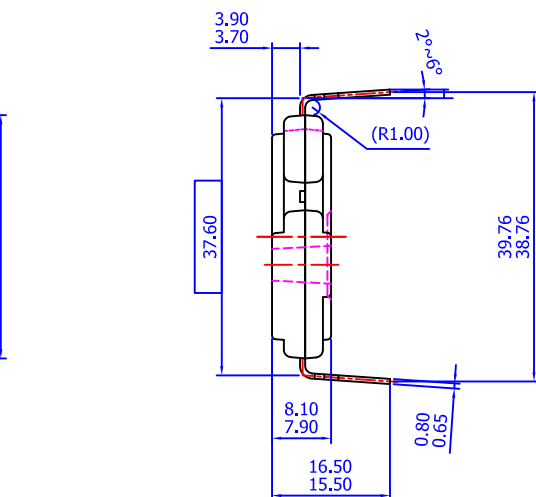
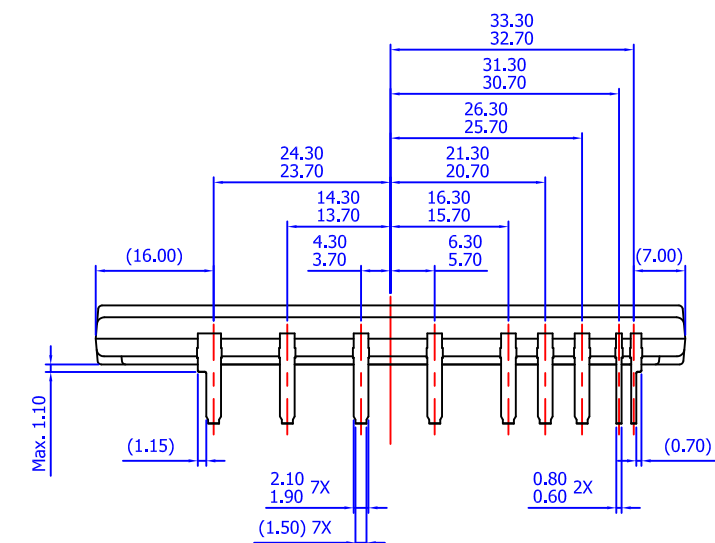
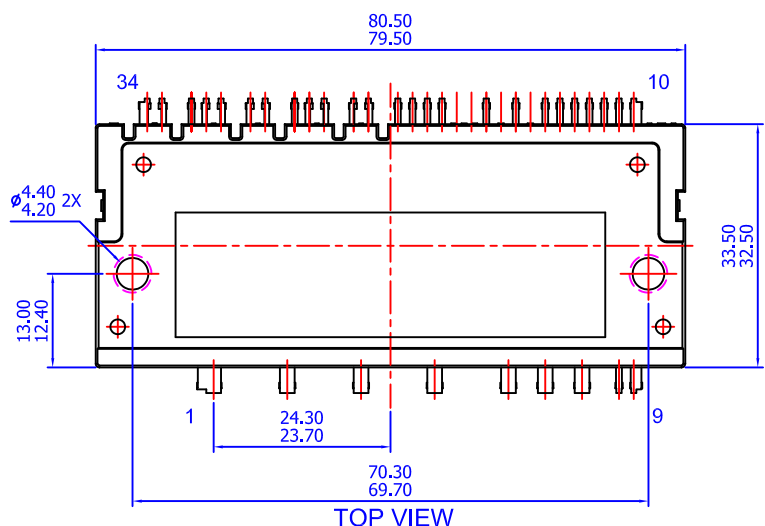
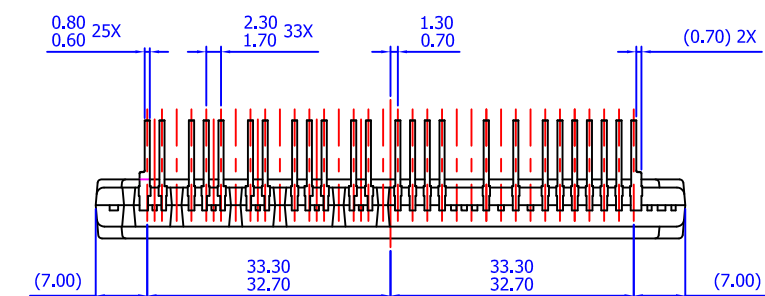


LAND PATTERN RECOMMENDATIONS

NOTES: UNLESS OTHERWISE SPECIFIED

- A) THIS PACKAGE DOES NOT COMPLY TO ANY CURRENT PACKAGING STANDARD
- B) ALL DIMENSIONS ARE IN MILLIMETERS
- C) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS
- D) PACKAGE SURFACE VOID SHALL NOT EXCEED 2.3 x 2.3 x 1.0mm
- E) () IS REFERENCE
- F) [] IS ASS'Y QUALITY
- G) DRAWING FILENAME: MOD34BAREV2.0
- H) FAIRCHILD SEMICONDUCTOR